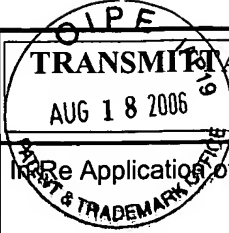
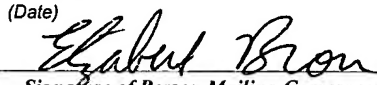
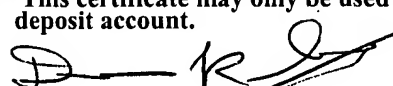
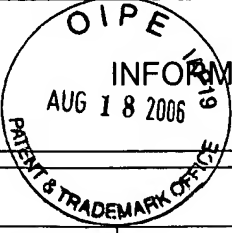
 TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT (Under 37 CFR 1.97(b) or 1.97(c))				Docket No. P-US058-A-MF	
Re Application Of: Hai Hong					
Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/763,594	January 22, 2004	Wollschlager, Jeffrey M.	32107	1732	
Title: Silicone Compositions, Methods of Making, and Uses Thereof					
Address to: Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450					
37 CFR 1.97(b)					
1. <input type="checkbox"/> The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.					
37 CFR 1.97(c)					
2. <input checked="" type="checkbox"/> The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:					
<div style="margin-left: 40px;"> <input type="checkbox"/> the statement specified in 37 CFR 1.97(e); </div>					
OR					
<div style="margin-left: 40px;"> <input checked="" type="checkbox"/> the fee set forth in 37 CFR 1.17(p). </div>					

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 TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT (Under 37 CFR 1.97(b) or 1.97(c))				Docket No. P-US058-A-MF	
Re Application of: Hai Hong					
Application No.	Filing Date	Examiner	Customer No.	Group Art Unit	Confirmation No.
10/763,594	January 22, 2004	Wollschlager, Jeffrey M.	32107	1732	
Title: Silicone Compositions, Methods of Making, and Uses Thereof					
Payment of Fee (Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))					
<input type="checkbox"/> A check in the amount of _____ is attached.					
<input checked="" type="checkbox"/> The Director is hereby authorized to charge and credit Deposit Account No. <u>502123</u> as described below.					
<input checked="" type="checkbox"/> Charge the amount of \$180.00					
<input checked="" type="checkbox"/> Credit any overpayment.					
<input checked="" type="checkbox"/> Charge any additional fee required.					
<input type="checkbox"/> Payment by credit card. Form PTO-2038 is attached.					
WARNING: Information on this form may become public. Credit card information should not be included on this form. Provide credit card information and authorization on PTO-2038.					
Certificate of Transmission by Facsimile*			Certificate of Mailing by First Class Mail		
I certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (Fa _____ (Date)			I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on <u>August 14, 2006</u> (Date)		
_____ Signature			 Signature of Person Mailing Correspondence		
_____ Typed or Printed Name of Person Signing Certificate			Elizabeth Brown Typed or Printed Name of Person Mailing Certificate		
*This certificate may only be used if paying by deposit account.					
 _____ Signature			Dated: August 14, 2006		
CC:					

	INFORMATION DISCLOSURE CITATION		ATTY DOCKET NO. P-US058-A-MF	APPLICATION NO. 10/763,594
			APPLICANT(S) Hai Hong	
			FILING DATE January 22, 2004	GROUP ART UNIT 1732

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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		3,598,467	08/10/1971	Durk Jon Pearson	350	3.5	
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		3,697,630	10/10/1972	Stanley Y. Yoshino	264	28	
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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		2002/0100256	08/01/2002	Trani, et al.	53	452	

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		Cohen, et al., "EFAB: Batch Production of Functional, Fully-Dense Metal Parts with Micron-Scale Features", Proc. 9th Solid Freeform Fabrication, The University of Texas at Austin, August 1998, pg. 161.
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		"Microfabrication - Rapid Prototyping's Killer Application", Rapid Prototyping Report, CAD/CAM Publishing, Inc., June 1999, pgs. 1-5.
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		F. Tseng, et al., "EFAB: High Aspect Ratio, Arbitrary 3-D Metal Microstructures Using a Low-Cost Automated Batch Process", 3rd International Workshop on High Aspect Ratio Microstructure Technology (HARMST'99), June 1999.
		Adam L. Cohen, et al., "EFAB: Low-Cost, Automated Electrochemical Batch Fabrication of Arbitrary 3-D Microstructures", Micromachining and Microfabrication Process Technology, SPIE 1999 Symposium on Micromachining and Microfabrication, September 1999.

EXAMINER:	DATE CONSIDERED:
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

INFORMATION DISCLOSURE CITATION	ATTY DOCKET NO. P-US058-A-MF	APPLICATION NO. 10/763,594
	APPLICANT(S) Hai Hong	
	FILING DATE January 22, 2004	GROUP ART UNIT 1732

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)		
		F. Tseng, et al., "EFAB: High Aspect Ratio, Arbitrary 3-D Metal Microstructures Using a Low-Cost Automated Batch Process", MEMS Symposium, ASME 1999 International Mechanical Engineering Congress and Exposition, November, 1999.
		Adam L. Cohen, "Electrochemical Fabrication (EFABTM)", Chapter 19 of the MEMS Handbook, edited by Mohamed Gad-El-Hak, CRC Press, 2002, pgs. 19/1 - 19/23.

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